

TOP LAYER DESCRIPTION	TABLE 1 PLATED THROUGH-HOLE REQUIREMENTS								
	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	COPPER THICKNESS	FINISHED HOLE DIAMETER
TIN-LEAD	0.81-0.86(0.85 DRILL)	0.025-0.050	0.005-0.015						0.725±0.075
IMMERSION TIN	0.81-0.86(0.85 DRILL)	0.025-0.050				0.9-1.5um			0.75±0.05
IMMERSION SILVER	0.81-0.86(0.85 DRILL)	0.025-0.050					0.15-0.65um		0.75±0.05
COPPER	0.81-0.86(0.85 DRILL)	0.025-0.050						0.003 MAX	0.75±0.05
GOLD	0.81-0.86(0.85 DRILL)	0.025-0.050		0.003-0.007	FLASH UP TO 0.0002				0.745±0.055

REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN180136	

Material and Plating:

Housing: PPA, UL94V-0.BLACK.

Contacts: High Conductivity Copper.

30u"Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Solder Tail over Nickel 50u" Min .

Electrical Characteristics:

Current Rating: 20 AMP@75°C ambient.

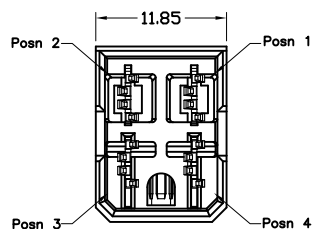
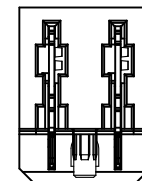
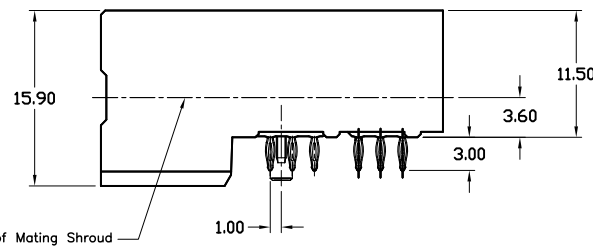
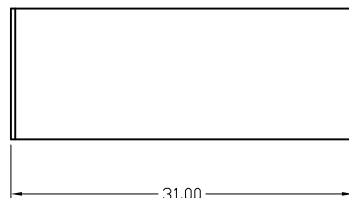
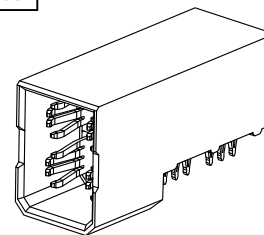
Dielectric Withstanding Voltage: AC 1500V For 1 minute.

Insulator Resistance: 10000MΩ min. at DC 500V.

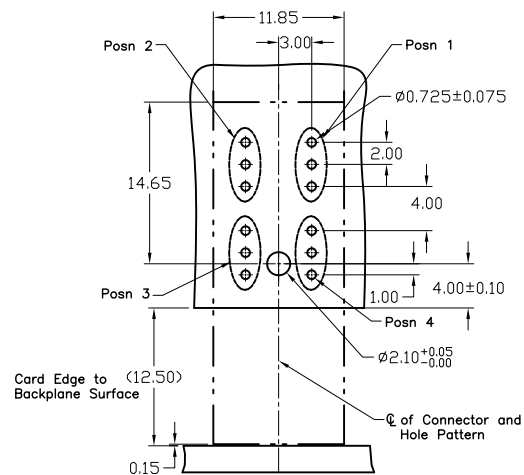
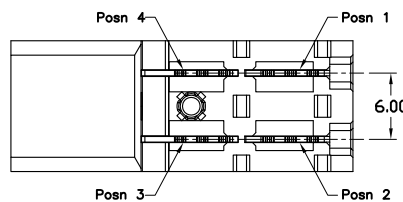
Contact Resistance: 1.0mΩ max. at DC 15AMP.

Operating Temperature: -55°C~+105°C.

***RoHS Compliant**



∅ of Mating Shroud 1.00



P.C. Board Layout

9113-N 2 x 2 Cxx P P A
 Series
 Position Per Column
 Column No.
 CB30:Dip Tin, Contact Au+Pd/Ni
 30: 30μ"
 Cxx: Selective Gold Plated
 00: G/F
 10: 10μ"
 15: 15μ"
 30: 30μ"
 A: Tray Packaging
 P: With Post
 N: Without Post
 Press fit Type

Tolerances	Dwg No.	9113-D0000-014
x = ±0.50	Projection	
.x = ±0.25	Unit	mm
.xx = ±0.15	Scale	1:1
	Drawn By	MXM 01/25'18

Title:
 9113-N Series
 2.00mm Pitch Power Conn.

OUPIN			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 9113-N2X2CxxPPA			
SHEET	1/1	Ver.No.	R3